FEATURES

► 7.05 V ultrastable shunt reference
► Low temperature coefficient: 0.2 ppm/°C
► Available in 4-pin TO-46 and 8-terminal LCC
► Typical reference noise for 10 Hz < f < 1 kHz: 1.84 μV rms
► Initial accuracy range: –300 mV to +250 mV
► Low dynamic impedance: 0.04 Ω in TO-46, 0.011 Ω in LCC
► External thermal insulator provided for TO-46
► Upgrade path for legacy LM399, now also in surface-mount technology (SMT)

APPLICATIONS

► Precision voltage reference for multimeters
► Calibration equipment voltage standards
► Laboratory measurement equipment
► Industrial monitor and control instrumentation
► Ultrastable data convertors

GENERAL DESCRIPTION

The ADR1399 precision shunt reference features excellent temperature stability over a wide range of voltage, temperature, and quiescent current conditions. A temperature stabilizing loop is incorporated with the active Zener on a monolithic substrate, which nearly eliminates changes in voltage with temperature. The subsurface Zener circuit is fully specified at a quiescent current \( I_{\text{REF}} \) of 3 mA and offers minimal noise (1.44 μV p-p, 0.1 Hz to 10 Hz) and excellent long-term stability (7 ppm/√kHz). The ADR1399 offers a lower output dynamic impedance (0.08 Ω) than the LM399, reducing the effects of shunt resistor \( R_{\text{SHUNT}} \) and the supply voltage variation on the reference output.

Ideal applications for the ADR1399 include ultrastable digital voltmeters, precision calibration equipment, and ultrarepeatable analog-to-digital converters (ADCs). The simplicity of the basic pin configurations is shown in Figure 1. The 8-terminal LCC version offers force and sense pins for lower dynamic impedance and for Kelvin sensing.

### Table 1. Related Products

<table>
<thead>
<tr>
<th>Model</th>
<th>Output Voltage (V)</th>
<th>Initial Accuracy Range (mV)</th>
</tr>
</thead>
<tbody>
<tr>
<td>ADR1399</td>
<td>7.05</td>
<td>–300 to +250</td>
</tr>
<tr>
<td>LTZ1000</td>
<td>7.2</td>
<td>–200 to +300</td>
</tr>
<tr>
<td>LM399</td>
<td>6.95</td>
<td>–200 to +350</td>
</tr>
<tr>
<td>LT1236</td>
<td>5 and 10</td>
<td>–2.5 to +2.5</td>
</tr>
</tbody>
</table>
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REVISION HISTORY

3/2022—Rev. 0 to Rev. A
Added 8-Terminal LCC................................................................. 1
Changes to Features Section.......................................................... 1
Added Figure 2, Renumbered Sequentially...................................... 1
Changes to General Description Section......................................... 1
Changes to Change in Reference Voltage with Current Parameter; Dynamic Impedance Parameter;
and Heater Supply Current, Still Air Parameter; Table 2................................................................. 3
Changes to Thermal Resistance Section and Table 4............................ 4
Added Figure 4 and Table 6, Renumbered Sequentially.................... 5
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Added Figure 8 and Figure 9........................................................... 6
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Changes to Thermal Resistance Section..........................................11
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Added Figure 41............................................................................. 14
Updated Outline Dimensions..........................................................15
Changes to Ordering Guide...............................................................16
Changes to Evaluation Boards.........................................................16

10/2021—Revision 0: Initial Version
## ELECTRICAL CHARACTERISTICS

\( T_A = 25^\circ C \), unless otherwise noted.

### Table 2.

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Conditions/Comments</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>ZENER REFERENCE VOLTAGE</strong></td>
<td>( V_Z )</td>
<td>3 mA ( \leq ) reference current (( I_{REF} )) ( \leq ) 13 mA</td>
<td>6.75</td>
<td>7.05</td>
<td>7.30</td>
<td>V</td>
</tr>
<tr>
<td><strong>CHANGE IN REFERENCE VOLTAGE WITH CURRENT</strong></td>
<td>( \Delta V_Z )</td>
<td>TO-46, 3 mA ( \leq ) ( I_{REF} ) ( \leq ) 13 mA</td>
<td>0.4</td>
<td>0.08</td>
<td>0.25</td>
<td>mV</td>
</tr>
<tr>
<td><strong>DYNAMIC IMPEDANCE</strong></td>
<td>( R_Z )</td>
<td>TO-46, 3 mA ( \leq ) ( I_{REF} ) ( \leq ) 13 mA</td>
<td>0.04</td>
<td>0.08</td>
<td>0.011</td>
<td>( \Omega )</td>
</tr>
<tr>
<td><strong>TEMPERATURE COEFFICIENT</strong></td>
<td>( \frac{dV}{dT} )</td>
<td>( I_{REF} = 3 ) mA, heater voltage (( V_H )) = 30 V, ( T_A = 0^\circ C ) to 70(^\circ)C</td>
<td>0.2</td>
<td>1</td>
<td>0.025</td>
<td>ppm/°C</td>
</tr>
<tr>
<td><strong>REFERENCE NOISE</strong></td>
<td>( e_N )</td>
<td>( I_{REF} = 3 ) mA, 0.1 Hz &lt; ( f ) &lt; 10 Hz</td>
<td>0.2</td>
<td>1.44</td>
<td>1.84</td>
<td>ppm p-p</td>
</tr>
<tr>
<td><strong>LONG-TERM STABILITY</strong></td>
<td>( \frac{dV}{dT} )</td>
<td>( V_H = 30 ) V, 22°C ( \leq ) ( T_A ) ( \leq ) 28°C, 1000 Hrs, ( I_{REF} = 3 ) mA</td>
<td>7</td>
<td>ppm/( \sqrt{\text{kHz}} )</td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>HEATER SUPPLY CURRENT, STILL AIR</strong></td>
<td>( I_H )</td>
<td>TO-46, ( T_A = 25^\circ C ), ( V_H = 30 ) V, ( I_{REF} = 3 ) mA</td>
<td>8.5</td>
<td>15</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>( T_A = -55^\circ C )</td>
<td>21</td>
<td>28</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>LCC, ( T_A = 25^\circ C ), ( V_H = 30 ) V, ( I_{REF} = 3 ) mA</td>
<td>20</td>
<td>25</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>( T_A = -55^\circ C )</td>
<td>40</td>
<td></td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td><strong>HEATER START-UP CURRENT</strong></td>
<td>( I_{HS} )</td>
<td>( V_H = 9.5 ) V to 30 V</td>
<td>110</td>
<td>140</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td><strong>HEATER SUPPLY VOLTAGE</strong></td>
<td>( V_H )</td>
<td>9.5</td>
<td>40</td>
<td>V</td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>WARM-UP TIME</strong></td>
<td>( t_{HOT} )</td>
<td>TO-46, LCC socketed, to ( \pm 0.05% ), ( V_H = 30 ) V</td>
<td>0.1</td>
<td>1</td>
<td>5</td>
<td>sec</td>
</tr>
<tr>
<td></td>
<td></td>
<td>To ( \pm 20 ) ppm</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>To ( \pm 10 ) ppm</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

1. Guarantee by design, not 100% production tested.

2. Guarantee correlated to moving air production test.
ABSOLUTE MAXIMUM RATINGS

Table 3.

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Rating</th>
</tr>
</thead>
<tbody>
<tr>
<td>Temperature Stabilizer</td>
<td>40 V</td>
</tr>
<tr>
<td>Reverse Breakdown Current</td>
<td>20 mA</td>
</tr>
<tr>
<td>Forward Current</td>
<td>1 mA</td>
</tr>
<tr>
<td>Reference to Substrate Voltage</td>
<td>-0.1 V</td>
</tr>
<tr>
<td>Temperature</td>
<td></td>
</tr>
<tr>
<td>Operating Range</td>
<td>0°C to 70°C</td>
</tr>
<tr>
<td>Storage Range</td>
<td>-65°C to +150°C</td>
</tr>
<tr>
<td>Lead, Soldering (10 sec)</td>
<td>300°C</td>
</tr>
</tbody>
</table>

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

Thermal performance is directly linked to the printed circuit board (PCB) design and operating environment. Close attention to the PCB thermal design is required.

Table 4. Thermal Resistance

<table>
<thead>
<tr>
<th>Package Type</th>
<th>$\theta_{JA}$</th>
<th>$\theta_{JC}$</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>TO-46</td>
<td>220</td>
<td>Not applicable</td>
<td>°C/W</td>
</tr>
<tr>
<td>2-Layer JEDEC Board</td>
<td>125</td>
<td>4</td>
<td>°C/W</td>
</tr>
</tbody>
</table>

1 The TO-46 case is not accessible beneath the Valox enclosure.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.
PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS

Figure 3. TO-46 Pin Configuration (The TO-46 Tab Is Indicated on the Plastic Enclosure by a Raised Ridge)

<table>
<thead>
<tr>
<th>Pin No.</th>
<th>Mnemonic</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>REF+</td>
<td>Positive Side of the Zener Reference (Typically with a Pull-Up Resistor to the Input Voltage ($V_{IN}$)).</td>
</tr>
<tr>
<td>2</td>
<td>REF−</td>
<td>Negative Side of the Zener Reference (Typically Grounded).</td>
</tr>
<tr>
<td>3</td>
<td>HEATER+</td>
<td>Positive Side of the Heater (Typically 15 V).</td>
</tr>
<tr>
<td>4</td>
<td>HEATER−</td>
<td>Negative Side of the Heater (Typically Grounded or −15 V).</td>
</tr>
<tr>
<td>Not applicable</td>
<td>CASE</td>
<td>CASE. Shorted to HEATER− at Pin 4.</td>
</tr>
</tbody>
</table>

Figure 4. LCC Pin Configuration

Table 6. LCC Pin Function Descriptions

<table>
<thead>
<tr>
<th>Pin No.</th>
<th>Mnemonic</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>−REFS</td>
<td>Negative Side of the Reference, Sense Pin. 2.2 mA flows out of this pin. Sense the negative reference at the −REFS pin.</td>
</tr>
<tr>
<td>2</td>
<td>−REFF</td>
<td>Negative Side of the Reference, Force Pin. Typically, 0.8 mA of current flows out of this pin.</td>
</tr>
<tr>
<td>3</td>
<td>HEATER+</td>
<td>Heater Positive Supply Pin.</td>
</tr>
<tr>
<td>4</td>
<td>NIC</td>
<td>Not Internally Connected. This pin is not connected internally.</td>
</tr>
<tr>
<td>5</td>
<td>HEATER−</td>
<td>Heater Negative Supply Pin (Substrate). Keep this pin voltage at or lower than other pins.</td>
</tr>
<tr>
<td>6</td>
<td>+REFF</td>
<td>Positive Side of the Reference, Force Pin. Typically, 0.8 mA of current flows into +REFF at the nominal overall set current of $I_{REF} = 3$ mA.</td>
</tr>
<tr>
<td>7</td>
<td>+REFS</td>
<td>Positive Side of the Reference, Sense Pin. 2.2 mA flows in. Sense the positive reference at the +REFS pin.</td>
</tr>
<tr>
<td>8</td>
<td>NIC</td>
<td>Not Internally Connected. This pin is not connected internally.</td>
</tr>
</tbody>
</table>
TYPICAL PERFORMANCE CHARACTERISTICS

Figure 5. Zener Reverse Characteristic (C_{COMP} is the Compensation Capacitor, R_{COMP} is the Compensation Resistor, H_{BYPASS} is the Capacitance Between HEATER+ and HEATER−, and I_{REF} is the Reference Current.)

Figure 6. Dynamic Impedance vs. Frequency

Figure 7. Stabilization Time, TO-46 (V_{REF} is the Reference Voltage.)

Figure 8. Stabilization Time, LCC

Figure 9. Initial Heater Current vs. Temperature

Figure 10. Final Heater Current vs. Temperature for Various Heater Voltages, TO-46
TYPICAL PERFORMANCE CHARACTERISTICS

Figure 11. Final Heater Current vs. Temperature for Various Heater Voltages, LCC

Figure 12. Heater Current vs. Time, TO-46

Figure 13. Heater Current vs. Time, LCC

Figure 14. Zener Spectral Noise with the Heater On

Figure 15. Zener Spectral Noise with the Heater Off

Figure 16. Response Time, No $R_{COMP}$ or $C_{COMP}$
TYPICAL PERFORMANCE CHARACTERISTICS

Figure 17. Response Time with \( R_{\text{COMP}} \) and \( C_{\text{COMP}} \)

Figure 18. 1 mA Load Step Response, No \( R_{\text{COMP}} \) or \( C_{\text{COMP}} \)

Figure 19. 1 mA Load Step Response, \( R_{\text{COMP}} = 5 \Omega \), \( C_{\text{COMP}} = 0.47 \mu \text{F} \)

Figure 20. 1 mA Load Step Response, \( R_{\text{COMP}} = 5 \Omega \), \( C_{\text{COMP}} = 1 \mu \text{F} \)

Figure 21. Reference Voltage vs. Temperature for 39 Devices, TO-46

Figure 22. Reference Voltage vs. Temperature for 39 Devices, TO-46, Referenced to 25°C Value
TYPICAL PERFORMANCE CHARACTERISTICS

Figure 23. Reference Voltage vs. Temperature for 40 Devices, LCC

Figure 24. Reference Voltage vs. Temperature for 40 Devices, LCC, Referenced to 25°C Value

Figure 25. Reference Voltage vs. Temperature for 40 Devices, LCC, Referenced to 25°C Value (Board 1)

Figure 26. Reference Voltage vs. Temperature for 40 Devices, LCC, Referenced to 25°C Value (Board 3)

Figure 27. Reference Voltage Long-Term Drift

Figure 28. 0.1 Hz to 10 Hz Peak-to-Peak Noise
TYPICAL PERFORMANCE CHARACTERISTICS

Figure 29. TO-46 Hysteresis, 0°C to 70°C, Heater On

Figure 30. TO-46 Hysteresis, 0°C to 70°C, Heater Off

Figure 31. TO-46 Hysteresis, −40°C to +125°C, Heater Off

Figure 32. LCC Hysteresis, 0°C to 70°C, Heater On

Figure 33. LCC Hysteresis, 0°C to 70°C, Heater Off

Figure 34. LCC Hysteresis, −40°C to +125°C, Heater Off
THEORY OF OPERATION

OPERATING SET TEMPERATURE

The ADR1399 contains a buried Zener diode with an approximate +2 mV/°C temperature coefficient, in series with an NPN, base emitter voltage (VBE) with an approximate −2 mV/°C temperature coefficient. The combined positive and negative temperature coefficients sum to a nominal 0 mV/°C overall temperature coefficient. There are two op-amp servo loops inside the ADR1399. One op-amp loop maintains a fixed ratio of Zener and VBE currents, with the total current set by an externally applied pull-up resistor or current source. Another op-amp loop maintains the device die at a nonadjustable set temperature of approximately 95°C, precluding the external ambient temperature fluctuations from affecting operating temperature. The entire system is provided in a simple 4-pin, hermetically sealed, TO-46 package and placed inside a plastic thermal insulator, which further keeps ambient fluctuations at bay and reduces the required heater power. If the ambient temperature exceeds the set temperature, the chip temperature control becomes open loop, and the temperature rejection of the device degrades while the excess ambient temperature condition persists.

With only an external supply and a pull-up resistor required for operation, the ADR1399 is simple to use. However, because it is so extremely stable, care must be taken to avoid degrading overall performance with external thermocouples and/or IR drops. For example, the heater current can be quite high; therefore, avoid sharing the heater current path with the Zener sense path. In addition, wherever metallurgical junctions are formed, such as where the device pins enter the board or where the reference voltage may be connectorized, try to ensure that junctions are paired and with similar thermal gradients. Parasitic thermocouples can simply add temperature dependencies from 1 μV/°C up to 40 μV/°C. See Application Note 86, A Standards Lab Grade 20-Bit DAC with 0.1ppm/°C Drift for additional information on thermoelectric potentials.

THERMAL RESISTANCE

The ADR1399 has an on-chip automated heater set to approximately 95°C. The TO-46 comes from the factory provided with a small plastic shield to keep air flow away from the reference. The factory included plastic air shield around the TO-46 reduces the effective net thermal resistance compared to a TO-46 without a shield. Techniques to increase thermal resistance include reducing solid copper planes in proximity to the device and elevating the device on its leads, approximately 1 cm above the board surface. A hatch ground on the bottom side of the board increases thermal resistance compared to a solid ground plane. The heater power for the LCC version is about 3× to 4× greater than the TO-46 version. To reduce heater power, keep copper away from the inner layers near the device and use a hatch ground on the bottom layer. The slotting method (Application Note 82, Understanding and Applying Voltage References), which was originally intended to isolate references from externally applied flexing on the board, helps to increase thermal resistance. Combining a copper keepout area, hatching the bottom side ground layer, and extreme slotting or isothermal islands keeps the PCB from drawing excessive heat from the ovenized reference. After assembly, an external enclosure or insulation can further reduce the heat loss and consequent power draw.

FORCE AND SENSE PINS

The LCC version adds four pins, two of which are not internally connected (NIC) and the other two split the active reference into force and sense action on the top and bottom of the shunt. The force pins (+REFF and −REFF) are similar to op amp outputs, and the sense pins (+REFS and −REFS) are similar to the feedback pins of an op amp in that they sense the output to close the feedback loop. However, they differ from op amps because the sense pins have 2.2 mA of bias current, which is orders of magnitude more than any op amp input, for example. Additionally, whereas an op amp is often designed in to have the output node at the correct voltage, the ADR1399 is designed to have the sense node at the most accurate voltage. For example, when some resistance is placed between the +REFF and +REFS pins, all the IR drop induced in the resistance, including the IR noise induced by approximately 10 pA/√Hz of current noise, is transferred to the +REFF pin and does not appear at the +REFS pin. For the most accurate reading of the reference voltage, sense the reference voltage at the +REFS and −REFS pins, and not at the force pins.

The ADR1399 is characterized typically at 3 mA, and between 3 mA and 10 mA. Of the 3 mA, 2.2 mA is allocated to the +REFS pins. 2.2 mA flows into the +REFS pin, and 2.2 mA flows out of the −REFS pin. The typical 3 mA is composed of an additional 0.8 mA flowing in and out of the +REFF and −REFF pins, respectively. At 10 mA, the sense pins remain at 2.2 mA and the extra 7.8 mA is regulated by the force pins.
Figure 35. LCC vs. TO-46 Block Diagrams
AVOIDING THERMOCOUPLE ERRORS

Thermocouples occur whenever two dissimilar metals form a junction. For example, the TO-46 package leads are made of Kovar™ and are usually soldered to a copper trace in a PCB design. Kovar copper junctions are known to cause thermocouple voltages of 35 μV/°C, which is about 25 times higher than the typical temperature coefficient of the ADR1399. To minimize thermocouple induced voltage errors, ensure that junctions in series with critical pins always see the same temperature as the corresponding junction in the return path. For the TO-46 of the ADR1399, this results in the need to avoid temperature gradients at the two points where the Zener pins contact the PCB.

SHUNT DYNAMIC IMPEDANCE AND CAPACITIVE LOAD

The ADR1399 offers reduced output shunt dynamic impedance over the LM399, which is often dismissed as an advancement that is not critical. However, considering the need for high stability in the presence of supply fluctuations and $R_{SHUNT}$ drift, the low dynamic impedance of the ADR1399 is advantageous.

Consider, for example, the effect of a 0.1% change in supply voltage on a 15 V supply running 3 mA into an ADR1399 through a 2.67 kΩ $R_{SHUNT}$. The extra supply voltage causes an extra 5.6 μA to flow, which, on the 40 mΩ dynamic impedance of the TO-46 version of the ADR1399, increases the reference voltage by 0.22 μV. The same supply shift onto an LM399 design and into its typical 0.5 Ω dynamic impedance induces a considerable 2.8 μV of reference shift. Therefore, the improvement in dynamic impedance allows a better opportunity for maintaining high stability in the most critical shunt reference output voltage. Similarly, one can calculate for the effects due to changes in the $R_{SHUNT}$ value.

One of the trade-offs of achieving the reduced dynamic impedance, however, is an increased sensitivity to direct capacitive loading. The LM399 is stable with a wide range of capacitive load. The ADR1399 starts to ring with direct capacitive loads of more than a few hundred pF, and oscillates with 10 nF directly. The ADR1399 is optimized for an external compensation series network of ~5 Ω and 1 μF, as shown in Figure 36 to Figure 41 (see the Typical Applications section). If updating a legacy design with excessive capacitance for the ADR1399, and there is nowhere to add a series 5 Ω, reduce the capacitance to less than 1 nF if possible. Another single element passive that works directly with the ADR1399 is a 10 μF tantalum capacitor, even though the series resistance can measure less than 5 Ω on an impedance analyzer.

With the 8-terminal LCC version of the ADR1399, including new force and sense pins, the dynamic impedance is lower. With the +REFF and +REFS shorted together, and the −REFF and −REFS shorted together, and sensing across the ±REFS pins, the dynamic impedance is 11 mΩ in magnitude, with 180 degrees of phase at low frequency, or −11 mΩ at DC.

TYPICAL APPLICATIONS

Figure 36 through Figure 41 show basic connections for single-supply, split supply, buffered references, negative heater supply with positive reference, and parallel references for lower noise operation.
APPLICATIONS INFORMATION

Figure 41. Basic Connections Using LCC with Force/Sense Pins
OUTLINE DIMENSIONS

Figure 42. 4-Pin Metal Header Package [TO-46]  
Dimensions Shown in Inches (Millimeters), Side and Bottom Views

Figure 43. 4-Pin TO-46 Thermal Shield  
Dimensions Shown in Inches

Figure 44. 8-Terminal Ceramic Leadless Chip Carrier LCC (E-8-2)  
Dimensions Shown in Millimeters
**OUTLINE DIMENSIONS**

**ORDERING GUIDE**

<table>
<thead>
<tr>
<th>Model</th>
<th>Temperature Range</th>
<th>Package Description</th>
<th>Package Option</th>
</tr>
</thead>
<tbody>
<tr>
<td>ADR1399KHZ</td>
<td>0°C to +70°C</td>
<td>4-Lead TO-46</td>
<td>05-08-1341</td>
</tr>
<tr>
<td>ADR1399KEZ</td>
<td>0°C to +70°C</td>
<td>8-Terminal LCC</td>
<td>E-8-2</td>
</tr>
</tbody>
</table>

1 Z = RoHS Compliant Part.

**EVALUATION BOARDS**

<table>
<thead>
<tr>
<th>Model</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>ADR1399E-EBZ</td>
<td>Evaluation Board for the ADR1399, LCC Package</td>
</tr>
<tr>
<td>ADR1399H-EBZ</td>
<td>Evaluation Board for the ADR1399, TO Package</td>
</tr>
</tbody>
</table>

1 Z = RoHS Compliant Part.
Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Analog Devices Inc.:
ADR1399KHZ  ADR1399H-EBZ  ADR1399KEZ  ADR1399E-EBZ